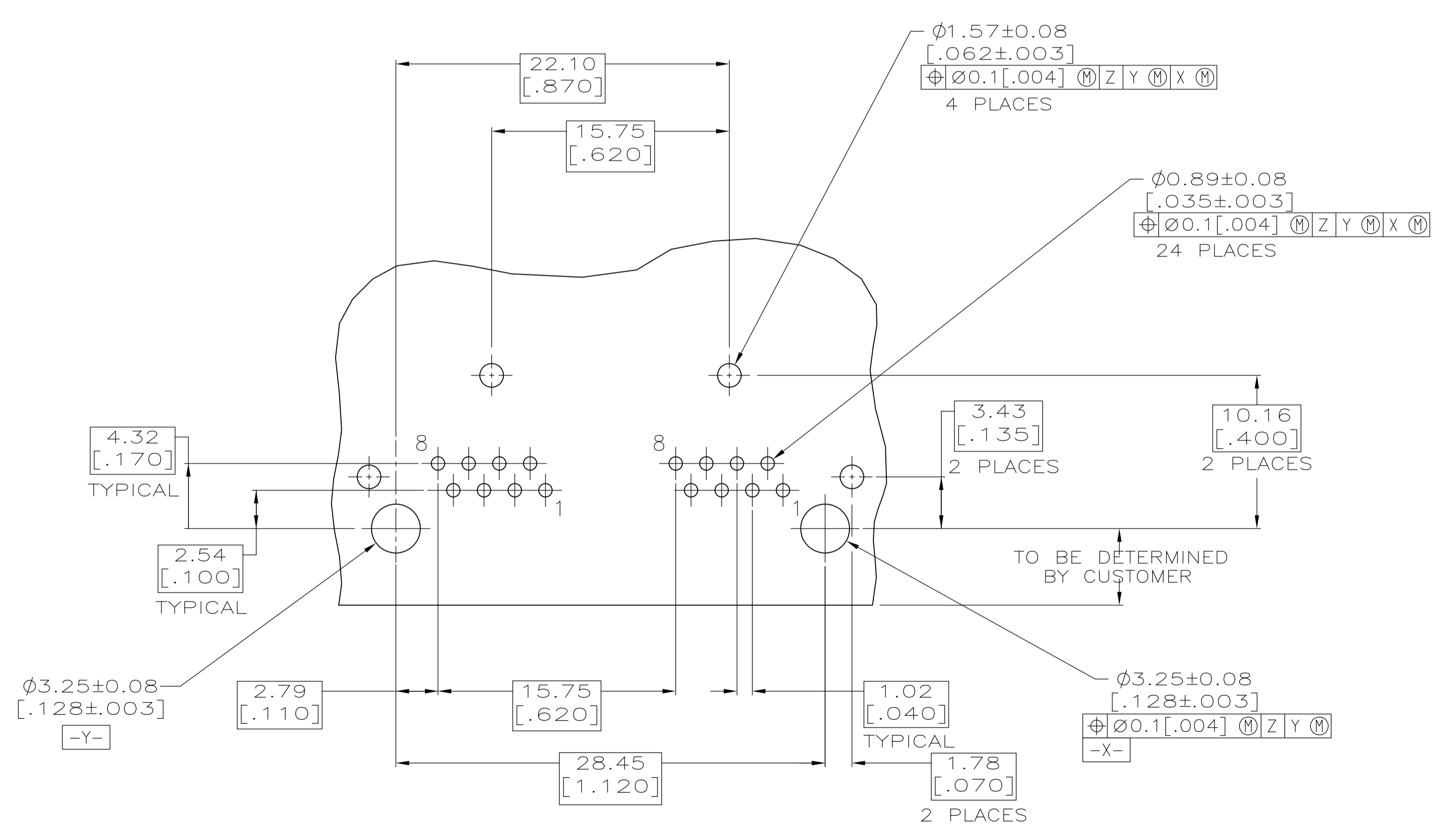


- △ MATERIAL: HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 SHIELD – 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm [.000050] MINIMUM SATIN NICKEL WITH 2.03µm [.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ TAPE&REEL PACKAGING WITH ANTISTATIC.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

△ T&R	6116522-2
TRAY	6116522-1
PACKAGE	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	L. VARELA - DOCKS 10JUN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm[inches]		CHK	J. WESTMAN 10JUN2005	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER 10JUN2005	PRODUCT SPEC	
0. PLC ± -	1. PLC ± -	APPLICATION SPEC		108-1163-4	
2. PLC ± 0.25[.01]	3. PLC ± 0.13[.005]	SIZE		114-2154	
4. PLC ± -	ANGLES ± -	WEIGHT		A1 00779 ©=6116522	
MATERIAL △	FINISH △	CUSTOMER DRAWING		SCALE	4:1
		SHEET		1 OF 1	
		REV		A1	